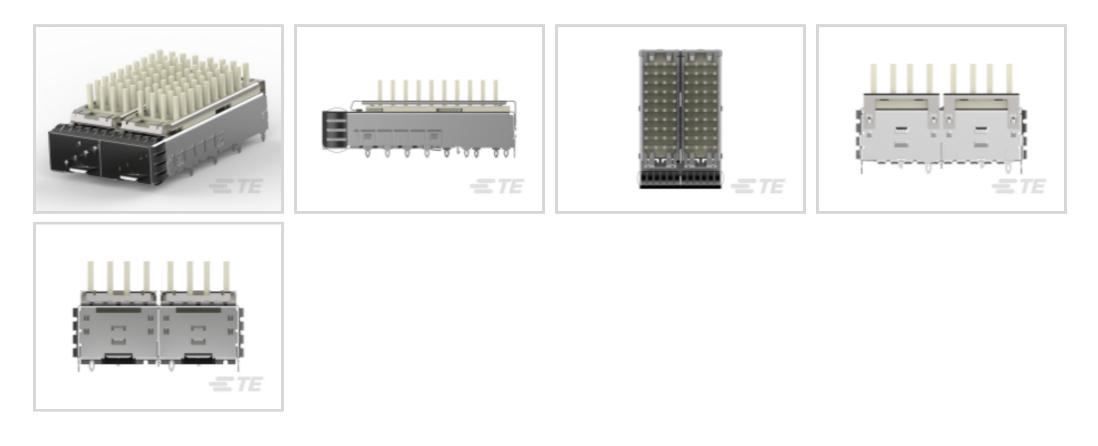
# 2198230-3 - ACTIVE

TE Internal #: 2198230-3 SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, External Springs, SFP+ Enhanced, 1 x 2, Pin, Heat Sink Height 9.1 mm [.358 in]

View on TE.com >

Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+



Pluggable I/O Product Type: Cage Assembly Data Rate (Max): 16 Gb/s

EMI Containment Feature Type: External Springs

Pluggable I/O Applications: SFP+ Enhanced

Thermal Accessory Type Included: Heat Sink

# Features

#### Product Type Features



| Form Factor                       | SFP+                  |
|-----------------------------------|-----------------------|
| Cage Туре                         | Ganged                |
| Pluggable I/O Product Type        | Cage Assembly         |
| Thermal Accessory Type Included   | Heat Sink             |
| Connector System                  | Cable-to-Board        |
| Sealable                          | No                    |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features            |                       |
| Port Matrix Configuration         | 1 x 2                 |
| Number of Ports                   | 2                     |
| Electrical Characteristics        |                       |
| Data Rate (Max)                   | 16 Gb/s               |
| Body Features                     |                       |
| Heat Sink Style                   | Pin                   |

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, External Springs, SFP+ Enhanced, 1 x 2, Pin, Heat Sink Height 9.1 mm [.358 in]



| Heat Sink Height Class  | Short   |
|---|---|
| Heat Sink Height  | 9.1 mm[.358 in]                                 |
| Termination Features  |   |
| Termination Method to Printed Circuit Board                     | Through Hole - Press-Fit                        |
| Mechanical Attachment   |   |
| PCB Mounting Style  | Through Hole - Press-Fit                        |
| Connector Mounting Type   | Board Mount                                     |
| Housing Features  |   |
| Cage Material   | Nickel Silver                                   |
| Dimensions  |   |
| Tail Length   | 2.05 mm[.081 in]                                |
| PCB Thickness (Recommended)                                     | 2.25 mm[.089 in]                                |
| Usage Conditions  |   |
| Operating Temperature Range                                     | -55 – 105 °C[-67 – 221 °F]                      |
| Operation/Application   |   |
| Heat Sink Compatible  | Yes   |
| For Use With Pluggable I/O Products                             | SFP+ SMT Connector                              |
| Pluggable I/O Applications                                      | SFP+ Enhanced                                   |
| Circuit Application   | Signal  |
| Packaging Features  |   |
| Packaging Method  | Box & Tray, Tray                                |
| Other   |   |
| EMI Containment Feature Type                                    | External Springs                                |
| Included Lightpipe  | No  |
|   |   |
| Product Compliance  |   |
| For compliance documentation, visit the product page on TE.com> |   |
| EU RoHS Directive 2011/65/EU                                    | Compliant                                       |
| EU ELV Directive 2000/53/EC                                     | Compliant                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016                   | No Restricted Materials Above Threshold         |
| EU REACH Regulation (EC) No. 1907/2006                          | Current ECHA Candidate List: JUNE 2022<br>(224) |

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, External Springs, SFP+ Enhanced, 1 x 2, Pin, Heat Sink Height 9.1 mm [.358 in]



Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Halogen Content

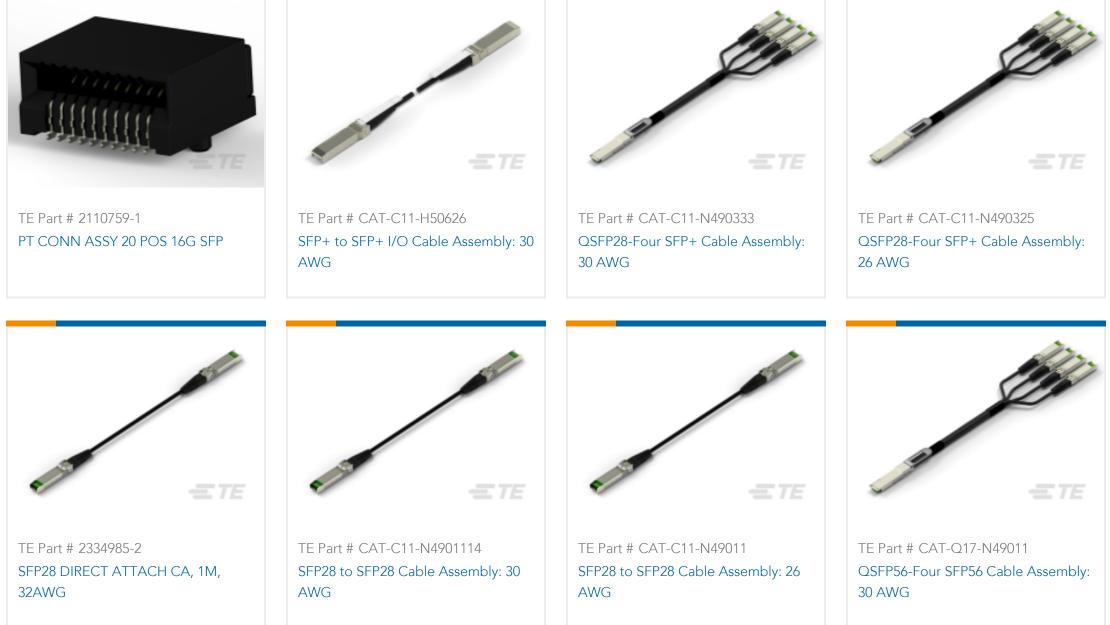
#### Solder Process Capability

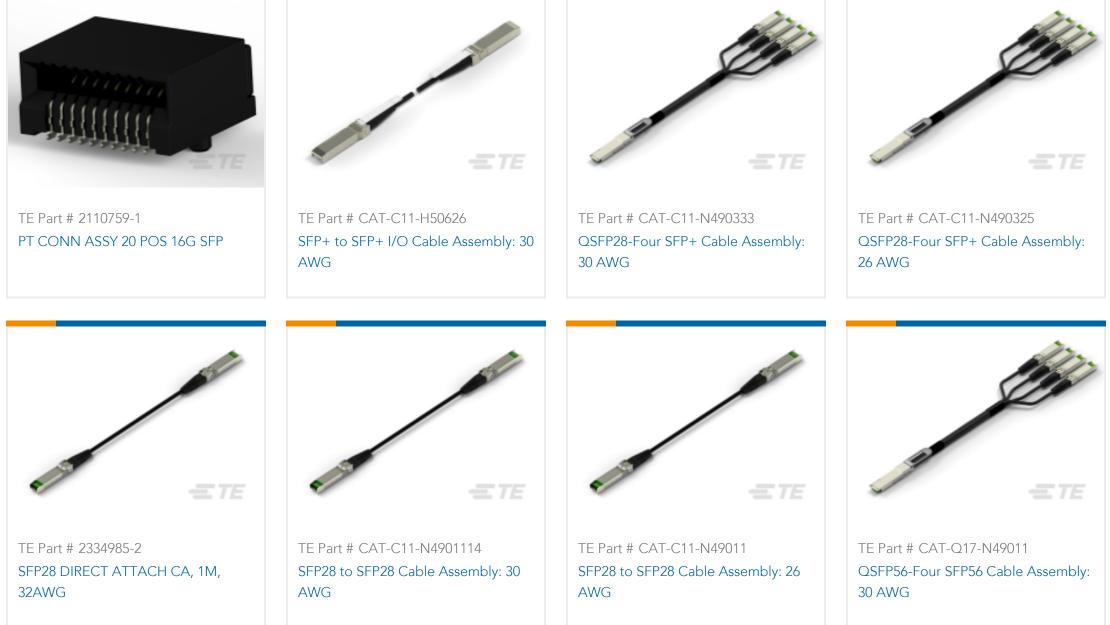
Not applicable for solder process capability

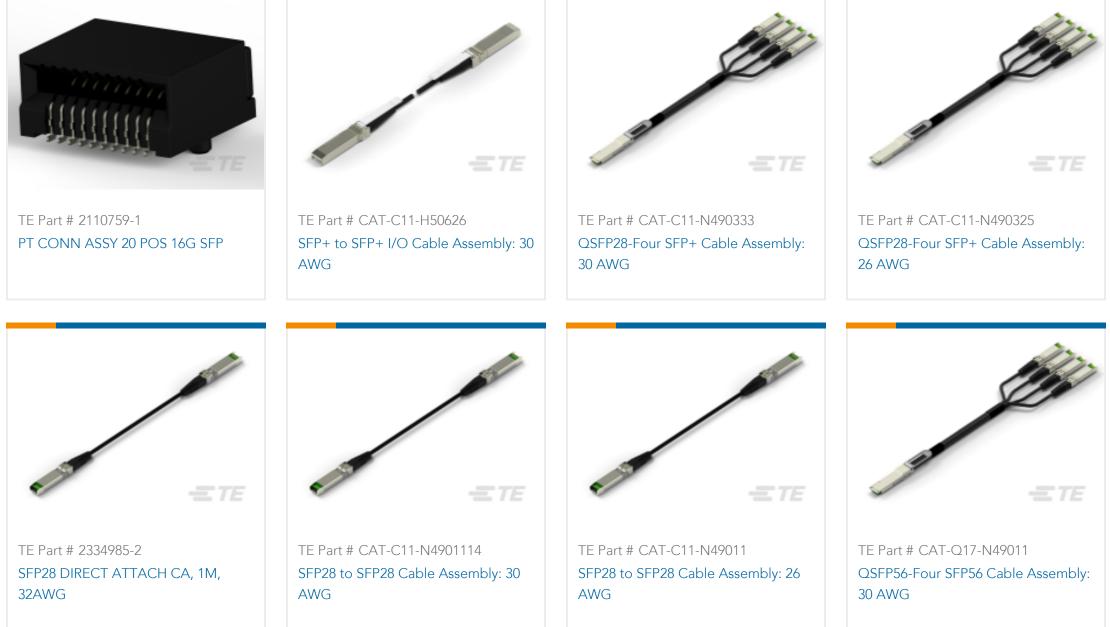
#### Product Compliance Disclaimer

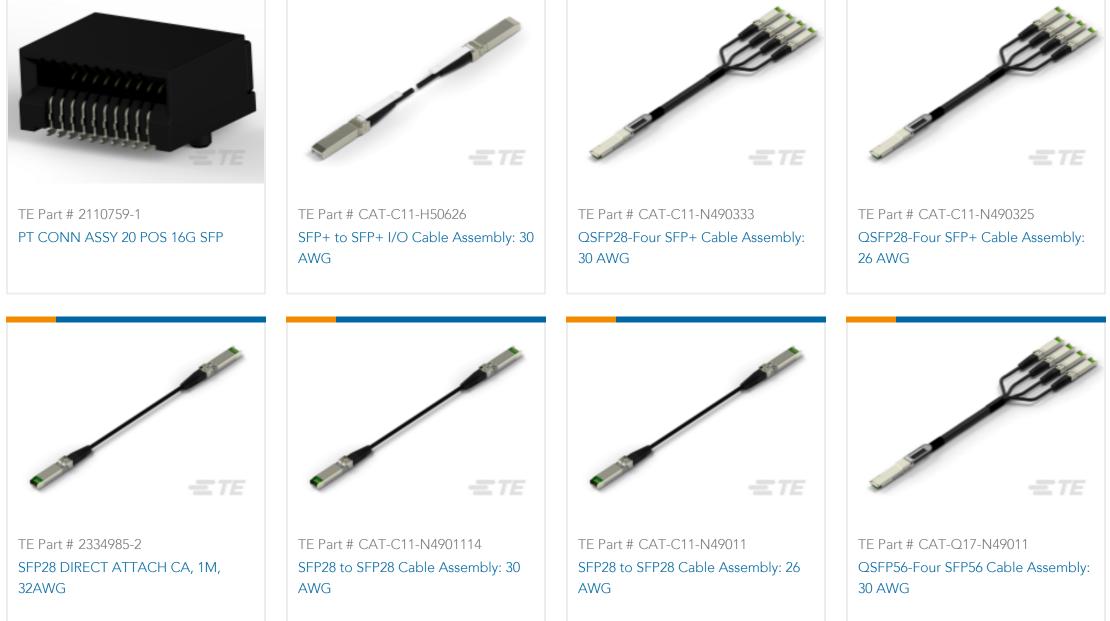
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

# **Compatible Parts**



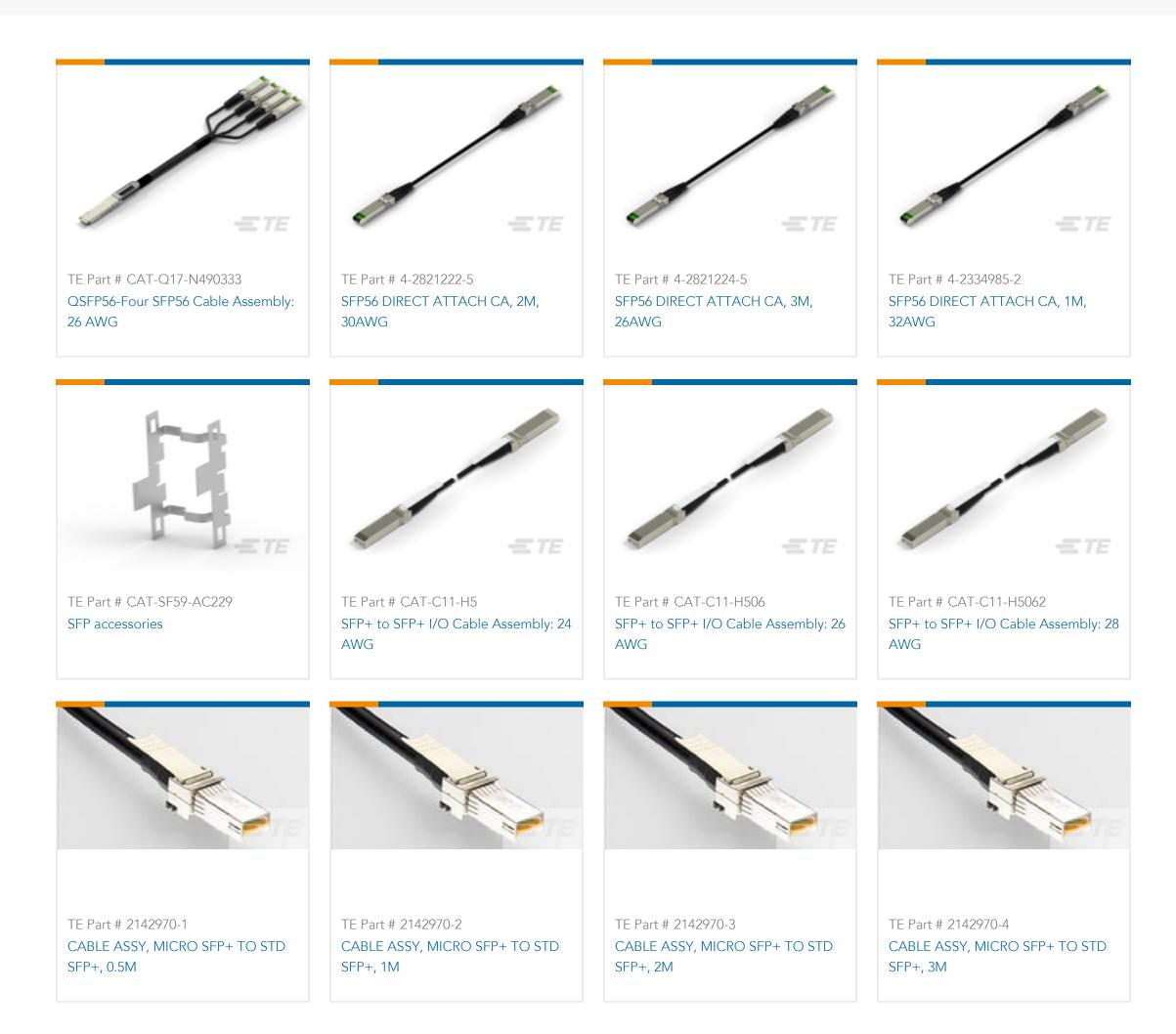




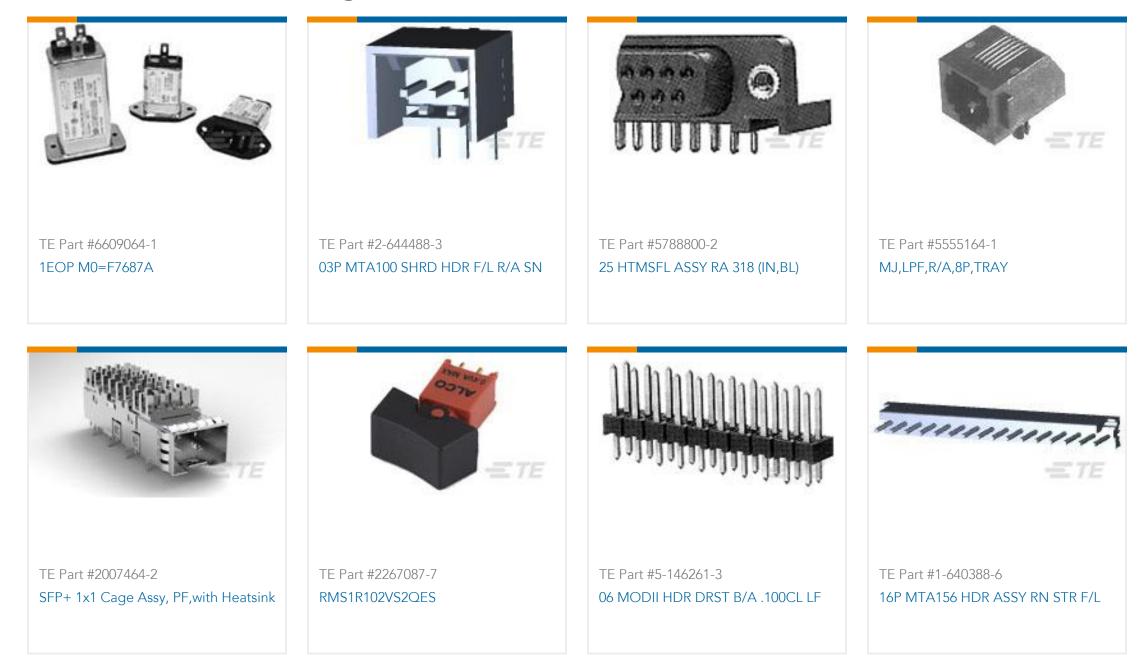


SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, External Springs, SFP+ Enhanced, 1 x 2, Pin, Heat Sink Height 9.1 mm [.358 in]





# Customers Also Bought



SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, External Springs, SFP+ Enhanced, 1 x 2, Pin, Heat Sink Height 9.1 mm [.358 in]





# Documents

# Product Drawings

## SFP+ Enhanced 1x2, Networking Heatsink

English

#### **CAD** Files

Customer View Model ENG\_CVM\_CVM\_2198230-3\_A.2d\_dxf.zip

English

#### 3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_2198230-3\_A.3d\_igs.zip

English

Customer View Model

#### ENG\_CVM\_CVM\_2198230-3\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English

Product Environmental Compliance

**TE Material Declaration** 

English